

PRODUCT NUMBER

71978-YXXLF

WHEN REQUIRED, ADD SUFFIX LETTER "LF"
INDICATES THE PRODUCT IS RoHS
COMPATIBLE, SEE NOTE 12

LATCHING
0= WITHOUT LATCH
1= STANDARD LATCH
2= LOW PROFILE LATCH

TOTAL NUMBER OF POSITIONS	
06	26
08	34
10	40
14	44
16	50
18	60
20	64

NOTES:

- 1 - HOUSING MAT'L : GLASS FILLED THERMOPLASTIC. UL94V-0 COLOR: BLUE
- 2 - PIN MATERIAL : PHOSPHOR BRONZE
- 3 - 0.76µm GOLD/GXT (PdNi WITH GOLD FLASH) ON CONTACT AREA
3.81µm TIN-LEAD ON TAIL.
UNDERPLATE : 1.27µm Ni MIN
- WHEN SUFFIX LETTER "LF" IS REQUIRED, 2µm MIN MATTE TIN OVER 1.27µm MIN NICKEL IS PROVIDED INSTEAD OF TIN-LEAD.
- 4 - PRODUCT PACKED IN TUBES
- 5 - 40N MIN LATCH RETENTION FORCE AT FIRST EXTRACTION
- 6 - TO DETERMINE DIMENSIONS :
N = NUMBER OF POSITIONS PER ROW
EXAMPLE : 8 POS N x 2.54 = 20.32mm
- 7 - NO CENTRAL SLOT ON POSITIONS 6 & 8
- 8 - NO LEFT POLARIZATION ON POSITIONS 06, 08, 10, 14.
- 9 - NO GROOVE ON POSITIONS 06, 08, 10, 14, 30, 34
- 10 - RETENTION LEGS LOCATED IN THE CENTER OF THE CONNECTOR
- 11 - MARKING : XX = YEAR CODE
YY = WEEK NUMBER
- 12 - RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

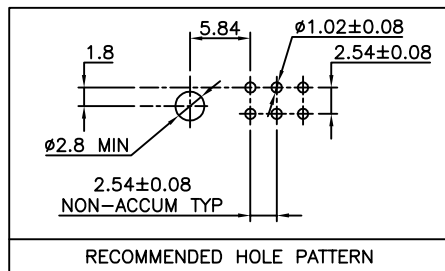
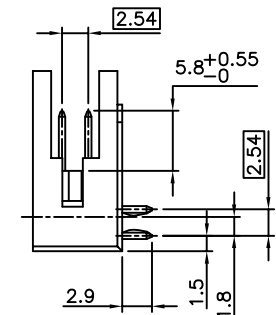
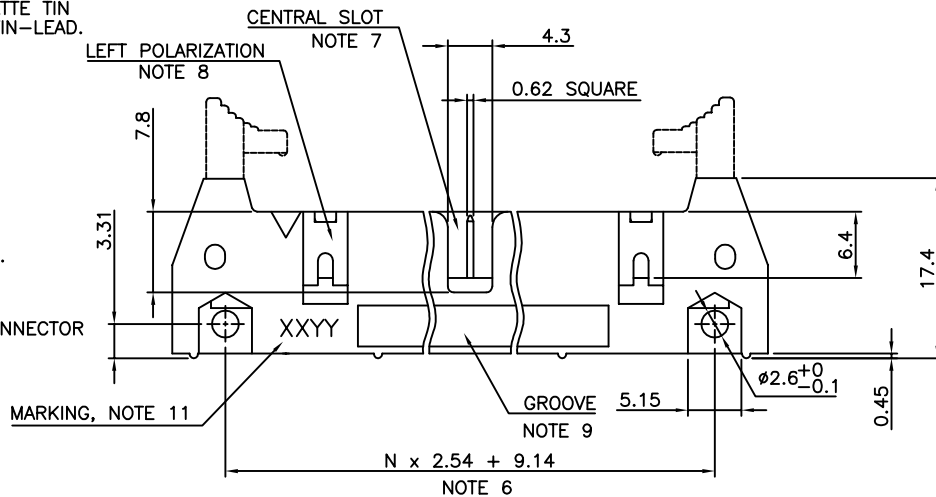
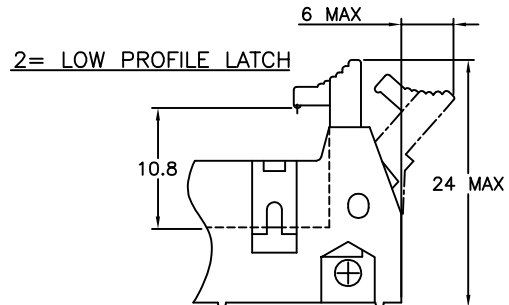
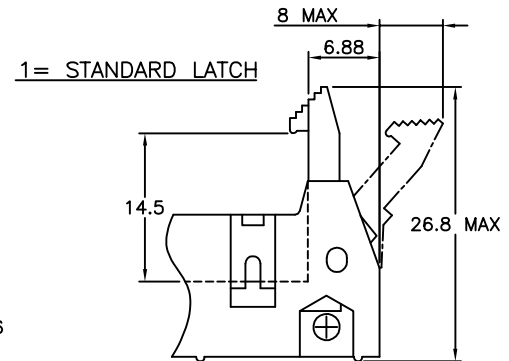
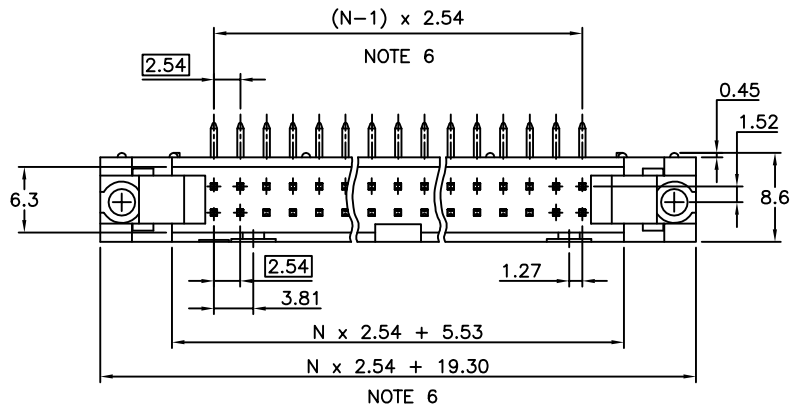
- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C ±5°C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.6mm MIN THICK CIRCUIT BOARD.

c - LABELING:

- MEETS PACKAGING SPECS AS PER GS-14-920
- d - LEGAL STATEMENT: SEE GS-22-008



mat'l. code		surface	tolerance	projection	product family
SEE NOTES		ISO 1302	ISO 406 ISO 1101		QUICKIE
ltr	ecn no	dr	date	title	
H	B-16860	LMU	14.01.27	SHR.EL.HEADER	
		angles	linear	mm	R.A, RETENTION LEGS
C	F60075	PNZ	96.01.25	scale 2:1	
D	F04-0389	JCO	04.12.22		dwg no
E	F06-0229	LMU	06.07.17		sheet 1 of 1 size
F	F07-0195	LMU	07.05.25		71978
G	F08-0146	YOV	08.04.11		A3
		appd	JCO		04.12.22
sheet		revision			
index		sheet			